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<b>TRANSMITTAL FORM</b>  (to be used for all correspondence after initial filing)	Application Number	10/824,723
	Filing Date	April 15, 2004
	First Named Inventor	L. Pierre deRochemont
	Art Unit	2827
	Examiner Name	TBD
Total Number of Pages in This Submission	Attorney Docket Number	10116-102DIV2

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Date	August 26, 2004

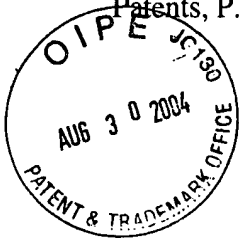
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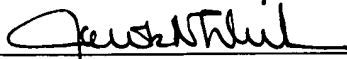
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Jacob N. Erlich  
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants: L. Pierre deRochemont, et al.

Examiner: TBD

Serial Number: 10/824,723

Group Art Unit: 2827

Filed: April 15, 2004

For: **METHOD OF MANUFACTURE OF CERAMIC COMPOSITE WIRING  
STRUCTURES FOR SEMICONDUCTOR DEVICES**

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Sir:

This Information Disclosure Statement (Form PTO-1449) is submitted under 37 CFR 1.97(b)(3).

**REMARKS**

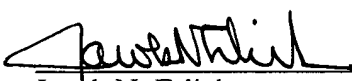
Applicant submits herewith an Information Disclosure Statement under 37 CFR 1.97(b)(3) before the mailing of a first office action on the merits. In view thereof, no fee is required. However, in the event fees are required, please charge any underpayment of fees to or credit any overpayment of fees to Deposit Account No. 03-2410, Order No. 10116-102.

The following information is presented in the event that a call may be deemed desirable by the Examiner:

JACOB N. ERLICH (617) 854-4000.

Respectfully submitted,  
L. Pierre deRochemont, et al., Applicants

Dated: August 26, 2004

By:   
Jacob N. Erlich  
Reg. No. 24,338  
Attorney for Applicants



**FORM PTO-1449**  
**U.S. DEPARTMENT OF COMMERCE**  
**PATENT AND TRADEMARK OFFICE**

ATTORNEY DOCKET NO.: 10116-102DIV2

APPLICATION SERIAL NO.: 10/824,723

GROUP ART UNIT: 2827

APPLICANT: L. Pierre deRochemont et al.

EXAMINER: TBD

FILING DATE: April 15, 2004

CONFIRMATION NO.: 6724

PRIORITY DATE: August 29, 1996

**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NO.	DATE	NAME	CLASS/SUB -CLASS	FILING DATE IF APPROPRIATE
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EXAMINER INITIAL	DOCUMENT NO.	DATE	NAME	CLASS/SUB- CLASS	TRANSLATION	
					YES	NO
	WO 89/08324	09/08/89	Digital Equipment Corp.	H01L 21/48		No
	WO 98/08672	03/05/98	deRochemont et al.	B32B 3/00		No
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	S. R. Foltyn, et al. "Pulsed Laser Deposition of Thick YBa <sub>2</sub> Cu <sub>3</sub> O <sub>7-d</sub> Films On Flexible Substrates." Proceedings of the International Workshop on Superconductivity, June 18-21, 1995, Maui, Hawaii.**
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	P. Arendt, et al. "Highly-Textured Ti-Ba-Ca-Cu-O Polycrystalline Superconducting Films on Ag Substrates," Science and Technology of Thin Film Superconductors 2, ed. By McConnell and Noufi, Plenum Press, New York, 1990.**

\* These patents are representative of the state of the art but published after or less than one year prior to Applicant's priority date. Therefore, if any such item is considered sufficiently relevant by the Examiner to the present invention, its possible "prior art" status against the present invention should be considered individually allowing for the prospect of swearing back or other priority determination.

\*\*These references were disclosed in prior Patent Application No. 09/344,682, filed June 25, 1999, now U.S. Patent No. 6,323,549, and, as such, copies thereof are not included pursuant to the provisions of 37 CFR 1.98(d).

**EXAMINER****DATE CONSIDERED**